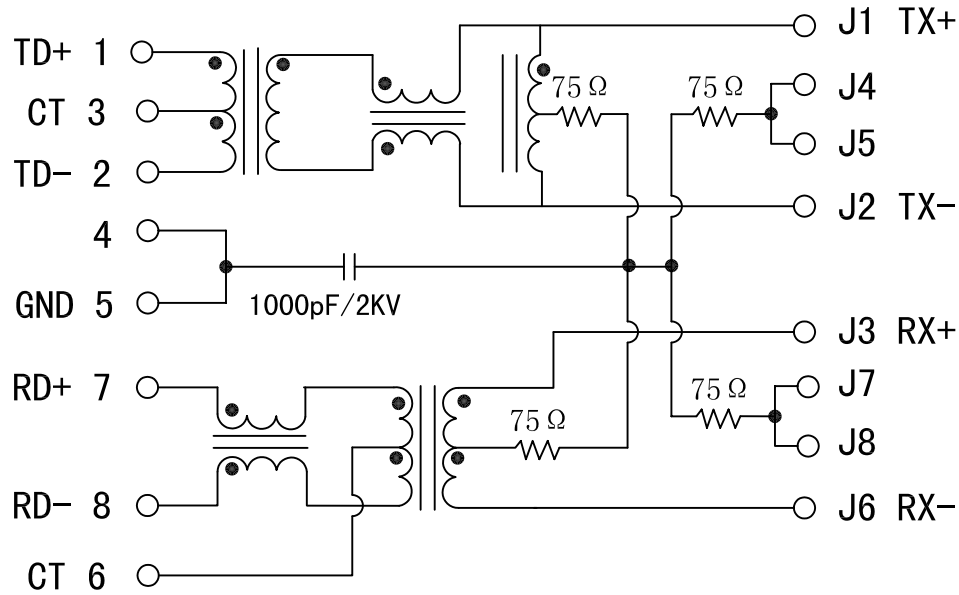


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		31/11/2009	

LAN CHIP SIDE

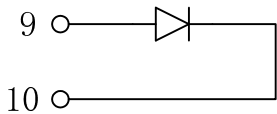


RJ CABLE SIDE

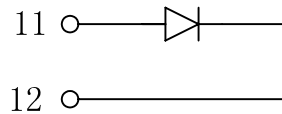
ELECTRICAL SPECIFICATIONS @25°C

- Turn Ratio ( $\pm 2\%$ ):  
TX=1CT:1      RX=1CT:1CT
- Inductance OCL:  
350uH MIN @ 100KHz, 0.1V, 8mA DC Bias
- Insertion Loss:  
-1.0dB MAX @ 1-65MHz
- Return Loss:  
-20dB MIN @ 1-10MHz  
-16dB MIN @ 10-30MHz  
-12dB MIN @ 30-60MHz  
-10dB MIN @ 60-100MHz
- Cross talk:  
-40dB MIN @ 1-30MHz  
-35dB MIN @ 30-60MHz  
-30dB MIN @ 60-100MHz
- Common Mode Rejection:  
-30dB MIN @ 1-50MHz  
-20dB MIN @ 50-150MHz
- Hipot Test: 1500Vrms MIN
- Operating Temperature Range: 0°C TO 70°C.

GREEN/LEFT LED



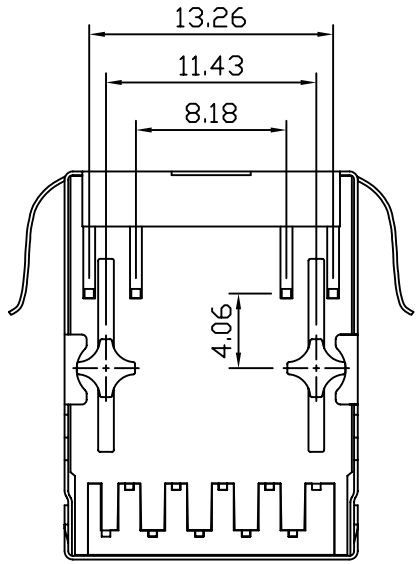
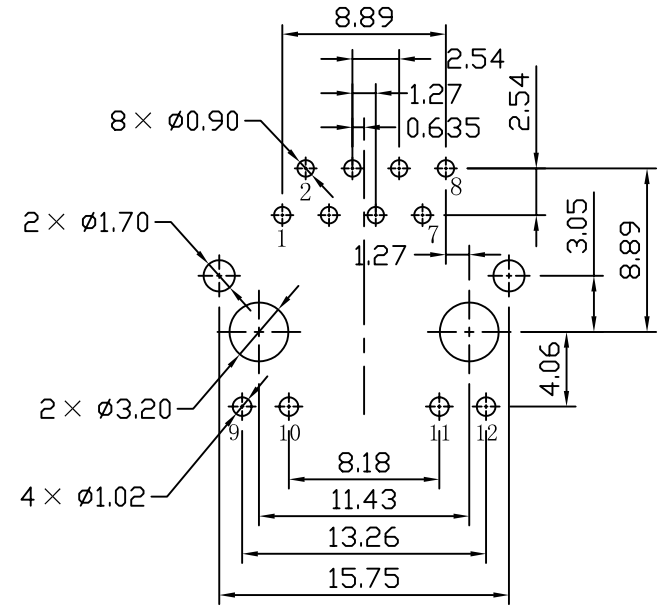
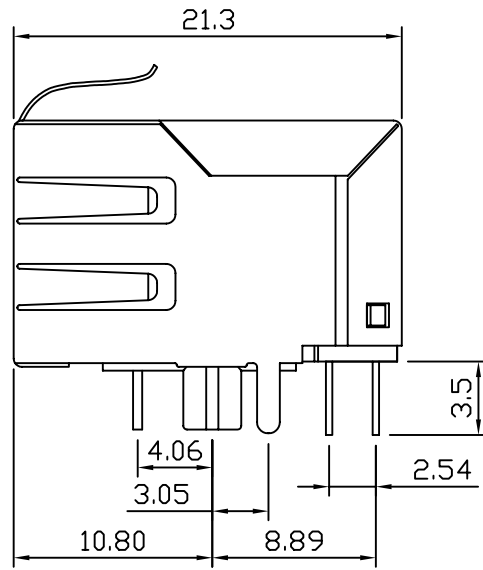
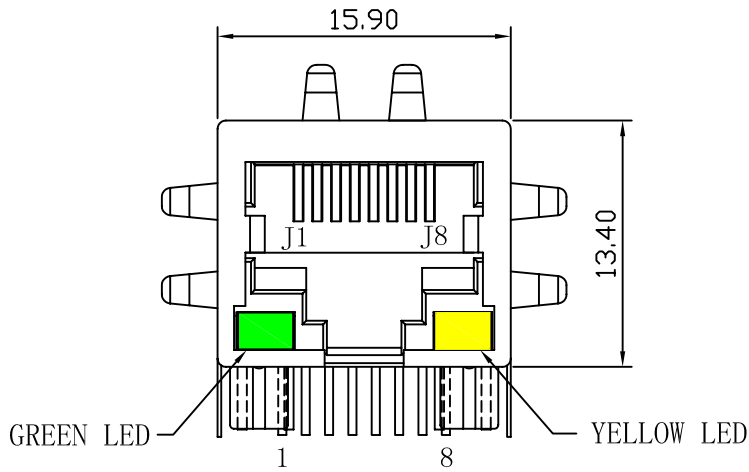
YELLOW/RIGHT LED



X:X ±0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.10	CHKD:	
X:XXX ±0.05	DR: TOM	TITLE: RJ45 Connector with 10/100 Base-TX Integrated Magnetics
ANGLES ±1°	UNIT: mm	PART NO.: LPJ0026GENL
	SCALE: 2/1	SHEET: 1/2
	REV: A	DWG NO.: LP09111303

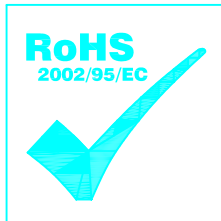
Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		13/11/2009	



NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:  
 Housing: Thermoplastic UL94V-0  
 Contact/Shield: Copper alloy  
 Shield plating: Nickel  
 Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 265°C Max  
 Wave solder tip temperature time: 5 Sec Max



X:X ±0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.10	CHKD:	
X:XXX ±0.05	DR: TOM	TITLE: RJ45 Connector with 10/100 Base-TX Integrated Magnetics
ANGLES ±1°	UNIT: mm	PART NO.: LPJ0026GENL
	SCALE: 2/1	SHEET: 2/2
	REV: A	DWG NO.: LP09111303